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This presentation contains certain forward-looking statements. Actual results may differ materially from those projected or implied in such forward-looking statements. Forward-looking information involves risks and uncertainties that could significantly affect expected results.
Overview
Austria Technologie & Systemtechnik AG (AT&S) is the largest producer of printed circuit boards in Europe and India, and also ranks among the industry leaders worldwide in innovation and the continuing development of printed circuit board manufacturing technologies. The AT&S Group employs more than 7,500 people around the world.

AT&S's main business divisions are Mobile Devices, Industrial & Automotive. Its core activity is the manufacture of high-end printed circuit boards – the nerve centres of so many electronic appliances.

AT&S is headquartered in Austria and carries out research and development in Austria and China. It has production facilities in Austria, China, India and Korea, a sales service and design centre in Germany, and a sales network spanning four continents.
Management and Owner

Free float 50,80%
Own shares 9,95%

Androsch Private foundation 21,51%
Dörflinger Private foundation 17,74%
Private foundations 39,17%

Board of management AT&S Group

DI (FH) Andreas Gerstenmayer Chairman/CEO
Mag. Thomas Obendrauf Chief Financial Officer/CFO
Ing. Heinz Moitzi Chief Technical Officer

Dr. Hannes Androsch Chairman of the Supervisory Board
# History

<table>
<thead>
<tr>
<th>Year</th>
<th>Events</th>
</tr>
</thead>
</table>
| 2011 | - Acquisition of land and start of construction of plant in Chongqing, China – AT&S’s seventh manufacturing facility.  
- Extension of capacity in Shanghai by about 30%. |
| 2010 | - Relocation of Group Headquarters from Vienna to Leoben-Hinterberg.  
- Ramp-Up plant II in Nanjangud. |
| 2009 | - Restructuring and reorientation of Leoben plant towards high-value industrial business.  
- Focusing Shanghai on high-end mobile devices segment. |
| 2008 | - Move to Vienna Stock Exchange (Prime Market). |
| 2006 | - Acquisition of Korean flexible printed circuit board producer Tofic Co. Ltd.: AT&S Korea |
| 2002 | - Start of production in new AT&S plant in Shanghai – one of the world’s most modern HDI* facilities. |
| 2000 | - Establishment of Nörvenich logistics and design centre in Germany |
- Purchase of Indal, India’s largest printed circuit board factory in Nanjangud: AT&S India. |
| 1987 | - Foundation of AT&S. |

* High Density Interconnect (laser-drilled printed circuit boards)
Locations

- 6 production facilities worldwide
- Purchasing & Sales Office: Hong Kong, China
- Design-Center: Nörvenich, Germany
- 16 Sales Offices on four continents
- About 7,500 employees
- R&D: Hinterberg and Shanghai – Cooperation with well-known partners from Industry and Science

- Leoben-Hinterberg:
  - Head Quarter
  - ~755 people

- Fehring:
  - ~380 people

- Klagenfurt:
  - ~110 people

- Ansan-Korea:
  - ~235 people

- Nanjangud-Indien:
  - ~1,040 people

- Shanghai:
  - ~4,900 people

- Chongqing:
  - ~ under construction
AT&S’s production facilities have different specialisations:

- Austria, India and Korea focus on small and middle batches for the industrial and automotive sector.
- China focuses on large batches for Mobile Device customers.

Within the last calendar year production capacity in China and India increased significantly:

- In the Shanghai plant capacity was expanded by about 30% to 710,000 m² per year by setting up additional production lines.
- In Nanjangud, India capacity was expanded to 380,000 m² per year by building a second plant.
Business Segments

Mobile Devices
AT&S is one of the world’s leading manufacturers of high-end printed circuit boards for smartphones, tablets, digital cameras, portable music players, etc. Its specialized know-how and manufacturing techniques have enabled it to satisfy ever more demanding customer requirements for increased functionality in a smaller space. Today, AT&S supplies eight of the ten largest smartphone manufacturers in the world.

Industry & Automotive
Industrial & Automotive serves a large number of customers with a variety of technological requirements. A high degree of flexibility and the ability to adapt to new technical specifications are crucial success factors in this business. AT&S printed circuit boards are used in such areas as measurement and control technology, medical technology, aerospace and industrial computers. AT&S sees further growth potential in the medical sector in particular.

Nearly all major suppliers of the European automotive industry are AT&S customers. AT&S focuses on the issues of safety, information, environment, e-mobility and affordable cars. The increasing use of electronics in cars is a driving force for further growth. Printed circuit boards are typically used for lane change assistants, adaptive cruise control and camera systems.

Advanced Packaging & Other
Other includes businesses around ECP® - Embedded Component Packaging. ECP® is a patented new microelectronic component packaging technology from AT&S, with proven advantages in applications where the highest levels of functional density, mechanical and thermal reliability and performance are demanded. AT&S has specifically developed ECP® technology to provide maximum advantage in the areas of miniaturization, reliability, integration and performance.
Historical Trends in Worldwide PCB Production

Growth Rates

Source: Prismark (2012)
Highly Fragmented Market

Overall Market Situation (2010)

- **Unimicron [T]**: 4%
- **Ibiden [J]**: 4%
- **Nippon Mektron [J]**: 4%
- **Tripod [T]**: 3%
- **TTM [US]**: 3%
- **SEMCO [K]**: 2%
- **Nanya PCB [T]**: 2%
- **Foxconn [T]**: 2%
- **Hannstar Board & GBM [T]**: 2%
- **KB PCB [C]**: 2%
- **Shinko Denki [J]**: 2%
- **Young Poong Group [K]**: 2%
- **CMK [J]**: 2%
- **Meiko [J]**: 2%
- **Viasystems [US]**: 2%
- **Daeduck Group [K]**: 2%
- **MFlex [US]**: 2%
- **Sumitomo Denko PCB [T]**: 2%
- **Fujikura [J]**: 1%
- **Corcom [T]**: 1%
- **Kinsus (+Printek) [T]**: 1%
- **WUS Group [T]**: 1%
- **AT&S [A]**: 1%
- **LG Innotek [K]**: 1%
- **Others**: 49%

**Median growth [%] (2009 to 2010):**
- **Top 10**: 35%
- **Top 25**: 26%
- **Top 50**: 24%
- **Top 100**: 26%

**Source**: Nakahara (2011); Strategy

*) Base: 2010 revenues
Overview PCB Market

Overall Market development


<table>
<thead>
<tr>
<th>Segment</th>
<th>2011</th>
<th>2016</th>
<th>CAGR</th>
</tr>
</thead>
<tbody>
<tr>
<td>IC Substrate</td>
<td>8.636</td>
<td>11.829</td>
<td>5.8%</td>
</tr>
<tr>
<td>Av. &amp; Security</td>
<td>1.462</td>
<td>2.425</td>
<td>2.5%</td>
</tr>
<tr>
<td>Medical</td>
<td>5.486</td>
<td>3.816</td>
<td>6.0%</td>
</tr>
<tr>
<td>Industrial</td>
<td>8.268</td>
<td>18.331</td>
<td>13.0%</td>
</tr>
<tr>
<td>Automotive</td>
<td>22.471</td>
<td>11.829</td>
<td>4.5%</td>
</tr>
<tr>
<td>Consumer</td>
<td>55.794</td>
<td>9.205</td>
<td>2.6%</td>
</tr>
<tr>
<td>Communication</td>
<td>2.787</td>
<td>7.727</td>
<td>6.6%</td>
</tr>
<tr>
<td>Computing</td>
<td>13.312</td>
<td>8.636</td>
<td>5.4%</td>
</tr>
</tbody>
</table>


<table>
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<tr>
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<td>IC Substrate</td>
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<td>Industrial</td>
<td>3.067</td>
<td>18.331</td>
<td>13.0%</td>
</tr>
<tr>
<td>Automotive</td>
<td>7.278</td>
<td>11.829</td>
<td>4.5%</td>
</tr>
<tr>
<td>Consumer</td>
<td>22.458</td>
<td>11.019</td>
<td>2.6%</td>
</tr>
<tr>
<td>Communication</td>
<td>55.794</td>
<td>13.237</td>
<td>6.6%</td>
</tr>
<tr>
<td>Computing</td>
<td>5.8</td>
<td>3.593</td>
<td>6.3%</td>
</tr>
</tbody>
</table>

Market Data 2012. Source: Prismark (2012); AT&S
Trend to Modular Concepts

„Electronics becomes part of the device rather than being the device“

Yesterday

Today

Tomorrow

Major Impact on Design Chain:

Sequential Design

Chip Design → Substrate Design → PCB Design

Concurrent Design

Module Design

Subst. Design → Concurrent Design → PCB Design → Subst. Design

® ATS AG
Construction of Chongqing Plant

Phase 1 under construction

Phase 2

Phase 3

admin. building under construction
Chongqing Phase 1 - June 2012
Distribution of Turnover in Q1 2012/13

Distribution of Turnover*
Ship to Party

- Austria+Germany: 45%
- Rest of Europe: 14%
- Asia: 11%
- Canada/USA: 29%

Distribution of Turnover*
by Headquarter

- Austria+Germany: 54%
- Rest of Europe: 12%
- Asia: 6%
- Canada/USA: 28%

*EUR 126m of revenues in Q1 2012/13

Figures are based on internal management information systems and are subject to change | Source: AT&S AG
**Segment Turnover**

**Mobile Devices lagging expectations**
Sales increased by 25%* (from EUR 56.0m to EUR 69.8m):
- Growing customer base in Asia
- Expansion of business with existing customers in US
- Capacity underutilisation in Shanghai

Positive outlook for Financial Year 2012/13 subject to stable macroeconomic conditions

**Industrial & Automotive Business stable**
Stable sales (from EUR 54.3m to EUR 55.9)
- Strong demand in the automotive supply industry
- Capacity utilisation in the Austrian plants in line with expectations
- Demand from major international customers in the industrial sector remains reserved

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* in comparison to Q1 2011/12

Figures are based on internal management information systems and are subject to change | Source: AT&S AG
## Financial Figures

<table>
<thead>
<tr>
<th>In EUR '000</th>
<th>Q1 2012/13</th>
<th>Q1 2011/12</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>CONSOLIDATED INCOME STATEMENT</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Revenues</td>
<td>126,034</td>
<td>110,463</td>
</tr>
<tr>
<td>Produced in Asia (in %)</td>
<td>73</td>
<td>66</td>
</tr>
<tr>
<td>Produced in Europe (in %)</td>
<td>27</td>
<td>34</td>
</tr>
<tr>
<td>EBITDA</td>
<td>21,057</td>
<td>18,185</td>
</tr>
<tr>
<td>EBITDA margin (in %)</td>
<td>16.7</td>
<td>16.5</td>
</tr>
<tr>
<td>EBIT</td>
<td>3,709</td>
<td>4,429</td>
</tr>
<tr>
<td>EBIT margin (in %)</td>
<td>2.9</td>
<td>4.0</td>
</tr>
<tr>
<td>Net income</td>
<td>517</td>
<td>2,061</td>
</tr>
<tr>
<td>Cash Earnings</td>
<td>17,867</td>
<td>15,890</td>
</tr>
</tbody>
</table>

Figures are based on internal management information systems and are subject to change. | Source: AT&S AG
# Financial Figures

<table>
<thead>
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<th>In EUR '000</th>
<th>Q1 2012/13</th>
<th>Q1 2011/12</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>CONSOLIDATED BALANCE SHEET</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Total assets</td>
<td>748,831</td>
<td>594,784</td>
</tr>
<tr>
<td>Total equity</td>
<td>300,080</td>
<td>227,946</td>
</tr>
<tr>
<td>Net debt</td>
<td>243,798</td>
<td>216,945</td>
</tr>
<tr>
<td>Net gearing (in %)</td>
<td>81.2</td>
<td>95.2</td>
</tr>
<tr>
<td>Net working capital</td>
<td>100,946</td>
<td>85,558</td>
</tr>
<tr>
<td>Net working capital / revenues (in %)</td>
<td>20.0</td>
<td>19.4</td>
</tr>
<tr>
<td>Equity ratio (in %)</td>
<td>40.1</td>
<td>38.3</td>
</tr>
</tbody>
</table>

Figures are based on internal management information systems and are subject to change | Source: AT&S AG
The Net Gearing is further declining.

Net investments of the Group are related to capacity and technology investments in Shanghai and the construction activities for the plant in Chongqing.

Figures are based on internal management information systems and are subject to change | Source: AT&S AG
Short-term borrowing increased due to reclassification of our outstanding bond.

Cash and Cash Equivalent increased due to the draw down of OeKB facility.

Financial Liabilities & Cash

<table>
<thead>
<tr>
<th>in EURm</th>
<th>31.03.2012</th>
<th>30.06.2012</th>
</tr>
</thead>
<tbody>
<tr>
<td>Short Term Borrowings</td>
<td>84,4</td>
<td>144,5</td>
</tr>
<tr>
<td>Long Term Borrowings</td>
<td>188,7</td>
<td>174,9</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalent</td>
<td>29,7</td>
<td>74,8</td>
</tr>
</tbody>
</table>
Investment Highlights
Stock Details

Listing
Vienna Stock Exchange, Prime Standard

Indices
ATX Prime, WBI

Reuters RIC (A)
ATSV.VI

Bloomberg (A)
ATS AV

# of shares issued
25.9 million

# of shares outstanding
23.3 million

Calendar
24.07.12 1st quarter 2012/13
26.07.12 Dividend payment date and ex-dividend date
23.10.12 2nd quarter 2012/13
22.01.13 3rd quarter 2012/13
08.05.13 Release of Annual Results 2012/13
AT&S—Last 5 years P/BV (x)

Source: FactSet as of 27-Apr-12, FactSet consensus

Note: 1 Multiples greater than 40.0x have been considered n/m

Note: 2 US-listed PCBs includes TTM, DDi, ViaSystems, and MFLEX

Note: 3 Asia-listed PCBs includes Flexium, Career Technology, Unimicron, Tripod Technology, Nan Ya and Ibiden Co
Investment Highlights

- Technology leader in HDI* any-layer printed circuit boards
- Close technology partnerships with international corporations
- Leading supplier to all big-name manufacturers of smartphones and tablets
- Leading supplier to the European automotive industry
- Successful niche-strategy in Austria
- Largest European printed circuit board manufacturer
- Competitive manufacturing capacities in Asia – most highly automated HDI plant in China
- Largest printed circuit board manufacturer in India
- High social and ethical standards in all facilities worldwide

* High Density Interconnect (laser-drilled printed circuit boards)
Thank you for your attention!